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*Dublin Institute of Technology*  
*Dublin, Ireland*

**Special Issue: Accreditation and Quality Assurance**  
**Guest Editor: Russel Jones**

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# The International Journal of ENGINEERING EDUCATION

## EDITOR-IN-CHIEF

**M. S. Wald**, Dublin Institute of Technology, Bolton Street, Dublin, Ireland  
Tel: (International +353 1) 4023635; Fax: (+353 1) 4023999; E-Mail: wald@dit.ie  
Website: <http://www.ijee.dit.ie>. Editor's direct phone: (+353 27) 61400. Mobile: (+49 172) 5106092

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